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Part Number:

0736422200

Status:

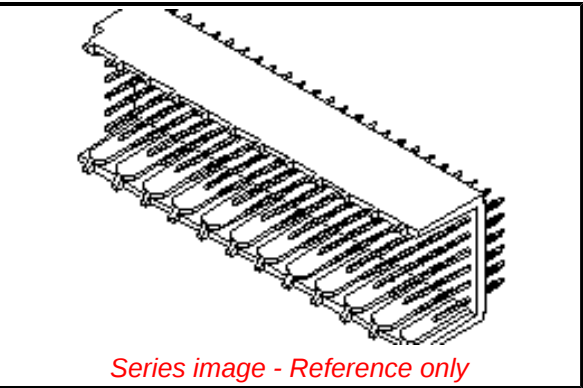
Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Backplane Header, Vertical, Press-Fit, Open End, 72 Circuits



Series image - Reference only

Documents:	
3D Model	Packaging Specification PK-70873-0818-001 (PDF)
Drawing (PDF)	Test Summary TS-73670-990-001 (PDF)
3D Model (PDF)	RoHS Certificate of Compliance (PDF)
Product Specification PS-73670-9999 (PDF)	

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73642
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800753193949
Physical	
Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	3.375/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

EU ELV	
Not Relevant	
EU RoHS	China RoHS
Compliant	
REACH SVHC	
Not Contained Per - D(2020)9139-DC (19 Jan 2021)	
Halogen-Free	
Status	
Low-Halogen	
For more information, please visit Contact US	
China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

73642 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling FAQ	
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.	
Global	
Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Removal Tool	621007600
Backplane Signal	622008502
Insertion Module	
Press-In Tool for 2.00mm Pitch HDM*	

		Board-to-Board Backplane Header
Electrical		
Current - Maximum per Contact	1.0A	
Data Rate	1.0 Gbps	
Real Signals (per 25mm)	75	
Shielded	No	
Voltage - Maximum	250V AC	
Solder Process Data		
Lead-freeProcess Capability	N/A	
Material Info		
Reference - Drawing Numbers		
Packaging Specification	PK-70873-0818-001	
Product Specification	PS-73670-9999	
Sales Drawing	SDA-73642-XXXX	
Test Summary	TS-73670-990-001	

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